

SPECIFICATION

Please amend Paragraph [0041] as follows:

[0041] Deposition of the film layer onto the shaped substrate comprises using the shaped substrate as the forming tool to pull the film layer onto the shaped substrate. Therefore, once formed, the shaped substrate can remain on the forming ~~foot~~tool to receive the film layer or be moved to a different forming tool. Although the shaped substrate may be used without a forming tool, it is desirable to employ the forming tool for structural integrity. During application of the film layer onto the shaped substrate, the film layer is heated in a similar manner as described above for the substrate, and is held in position relative to the holding fixture and substrate using, for example, clamps. A vacuum is then pulled through the shaped substrate to pull the film layer onto the substrate to form a layered article. In various embodiments, a tie-layer may be introduced between the substrate and the film layer to improve adhesion between the substrate and the film layer. When a tie-layer is employed, it is disposed on the film layer, between the shaped substrate and the film layer, before the film layer is thermoformed onto the shaped substrate, such that, when the film layer is pulled onto the shaped substrate, the tie-layer is also pulled on (and possibly extrudes into) the shaped substrate. This tie-layer can assist in bonding the shaped substrate and the film layer together.